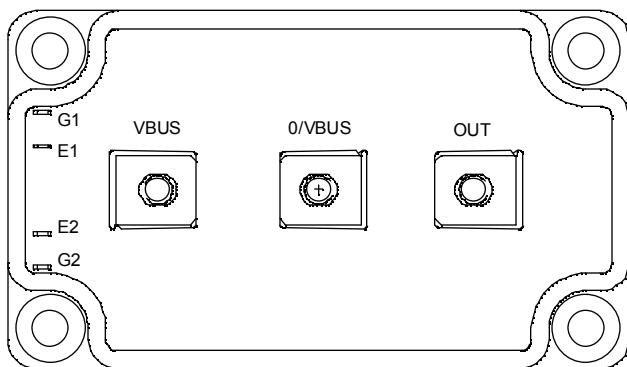
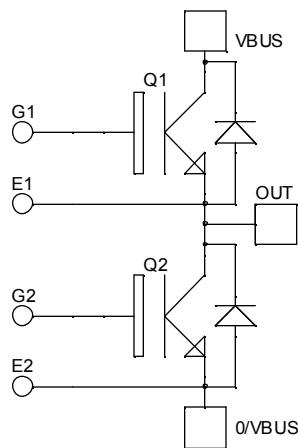


Phase leg
**Fast Trench + Field Stop IGBT®
 Power Module**

V_{CES} = 1200V
I_C = 200A @ T_c = 80°C



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V _{CES}	Collector - Emitter Breakdown Voltage	1200	V
I _C	Continuous Collector Current	T _c =25°C	A
		T _c =80°C	
I _{CM}	Pulsed Collector Current	T _c =25°C	400
V _{GE}	Gate – Emitter Voltage	±20	V
P _D	Maximum Power Dissipation	T _c =25°C	890
RBSOA	Reverse Bias Safe Operating Area	T _j = 125°C	400A @ 1100V

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- Fast Trench + Field Stop IGBT® Technology
 - Low voltage drop
 - Low tail current
 - Switching frequency up to 20 kHz
 - Soft recovery parallel diodes
 - Low diode VF
 - Low leakage current
 - Avalanche energy rated
 - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration

Benefits

- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCESat
- Low profile
- RoHS Compliant

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
I_{CES}	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}$, $V_{CE} = 1200\text{V}$				350	μA
$V_{CE(\text{sat})}$	Collector Emitter Saturation Voltage	$V_{GE} = 15\text{V}$	$T_j = 25^\circ\text{C}$	1.4	1.7	2.1	V
		$I_C = 200\text{A}$	$T_j = 125^\circ\text{C}$		2.0		
$V_{GE(\text{th})}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$, $I_C = 3 \text{ mA}$		5.0	5.8	6.5	V
I_{GES}	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}$, $V_{CE} = 0\text{V}$				500	nA

Dynamic Characteristics

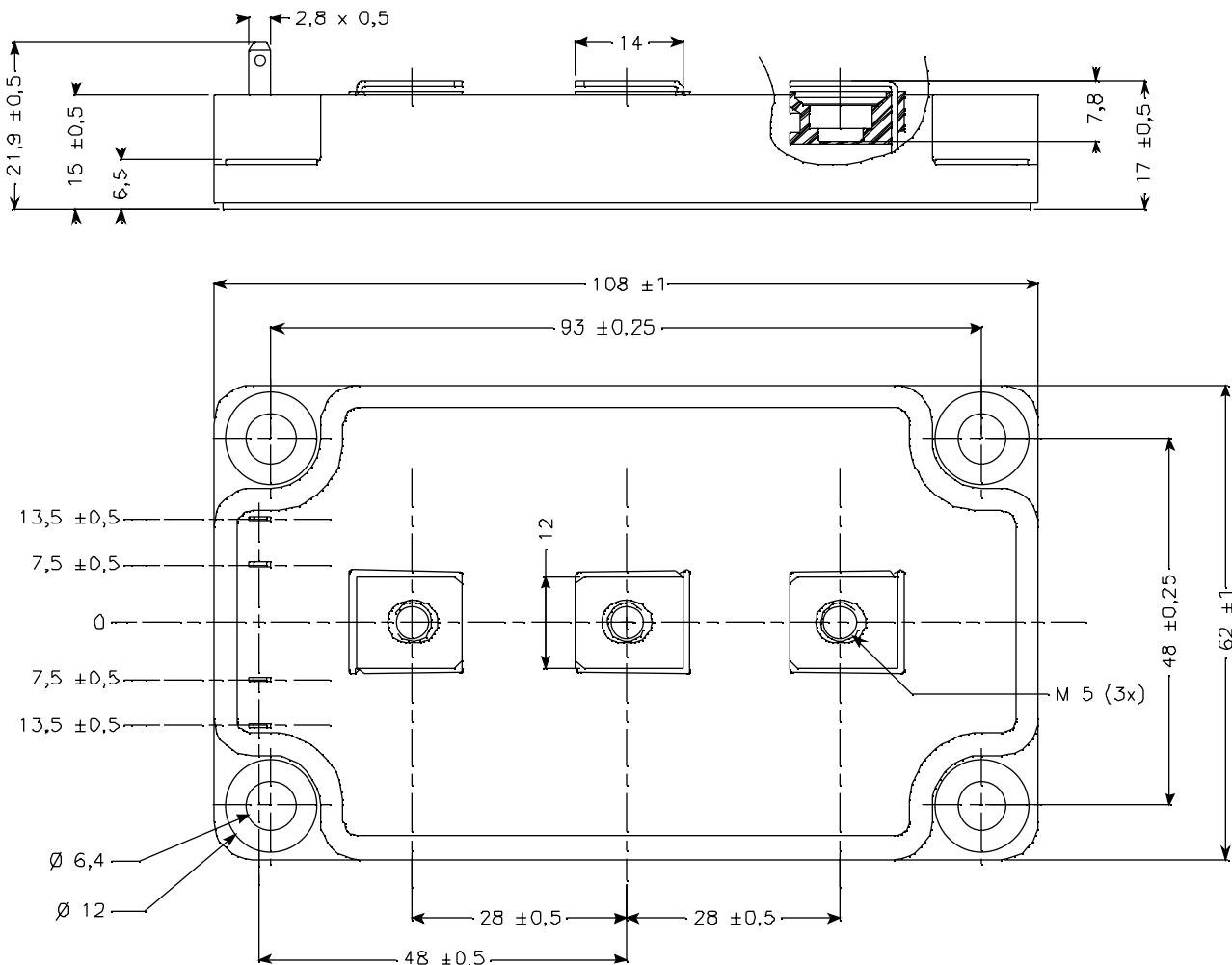
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
C_{ies}	Input Capacitance	$V_{GE} = 0\text{V}$ $V_{CE} = 25\text{V}$ $f = 1\text{MHz}$		14			nF
C_{oes}	Output Capacitance			0.8			
C_{res}	Reverse Transfer Capacitance			0.6			
$T_{d(on)}$	Turn-on Delay Time	$\text{Inductive Switching (25}^\circ\text{C)}$ $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 600\text{V}$ $I_C = 200\text{A}$ $R_G = 2.7\Omega$		260			ns
T_r	Rise Time			30			
$T_{d(off)}$	Turn-off Delay Time			420			
T_f	Fall Time			70			
$T_{d(on)}$	Turn-on Delay Time	$\text{Inductive Switching (125}^\circ\text{C)}$ $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 600\text{V}$ $I_C = 200\text{A}$ $R_G = 2.7\Omega$		290			ns
T_r	Rise Time			50			
$T_{d(off)}$	Turn-off Delay Time			520			
T_f	Fall Time			90			
E_{on}	Turn on Energy	$V_{GE} = \pm 15\text{V}$	$T_j = 125^\circ\text{C}$		20		mJ
E_{off}	Turn off Energy	$V_{Bus} = 600\text{V}$	$I_C = 200\text{A}$		20		
		$R_G = 2.7\Omega$	$T_j = 125^\circ\text{C}$				

Reverse diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit	
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			1200			V	
I_{RM}	Maximum Reverse Leakage Current	$V_R = 1200\text{V}$	$T_j = 25^\circ\text{C}$			350	μA	
			$T_j = 125^\circ\text{C}$			600		
I_F	DC Forward Current		$T_c = 80^\circ\text{C}$		200		A	
V_F	Diode Forward Voltage	$I_F = 200\text{A}$ $V_{GE} = 0\text{V}$	$T_j = 25^\circ\text{C}$		1.6	2.1	V	
			$T_j = 125^\circ\text{C}$		1.6			
t_{rr}	Reverse Recovery Time	$I_F = 200\text{A}$ $V_R = 600\text{V}$ $di/dt = 2500\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		170		ns	
			$T_j = 125^\circ\text{C}$		280			
Q_{rr}	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$		18		μC	
			$T_j = 125^\circ\text{C}$		36			
E_r	Reverse Recovery Energy		$T_j = 25^\circ\text{C}$		10		mJ	
			$T_j = 125^\circ\text{C}$		18			

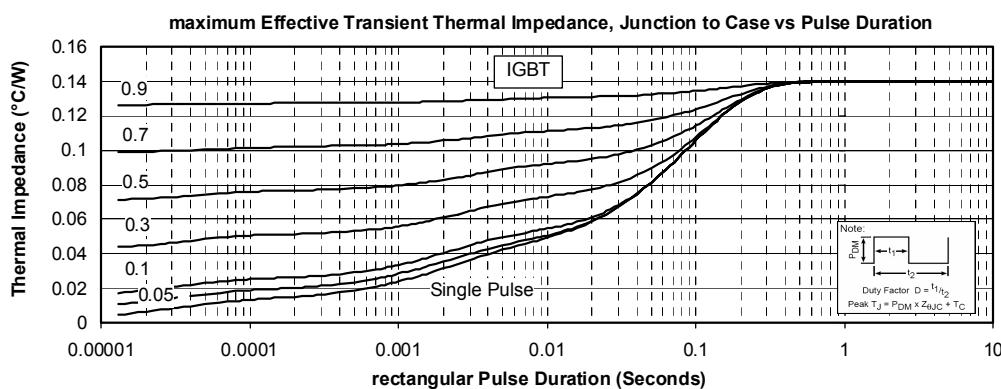
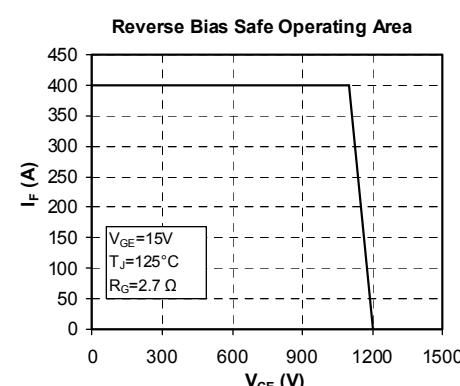
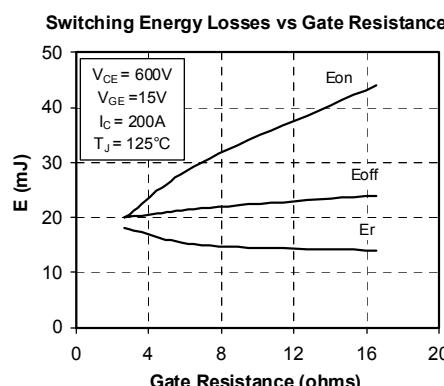
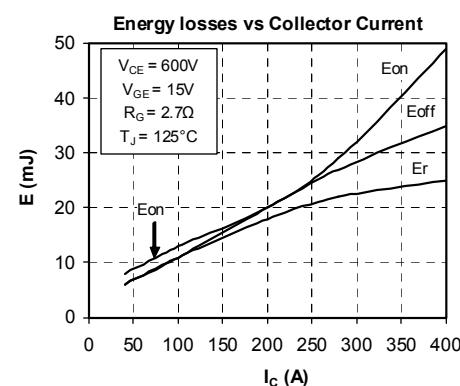
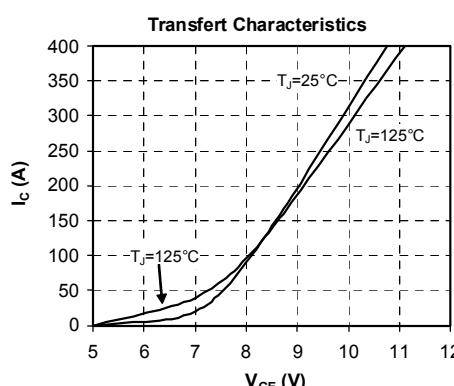
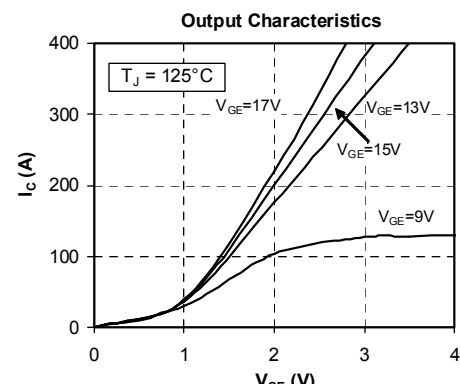
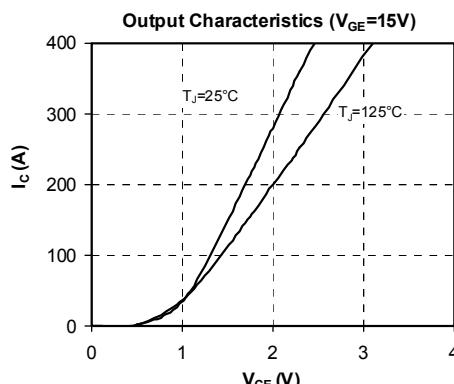
Thermal and package characteristics
Symbol **Characteristic**

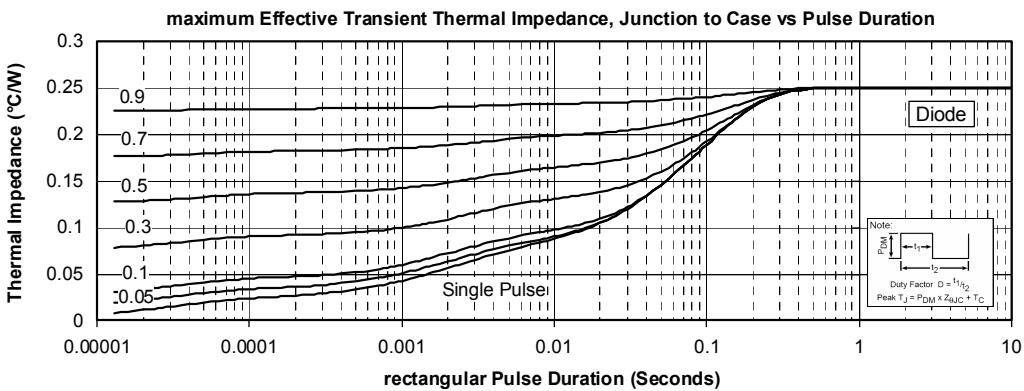
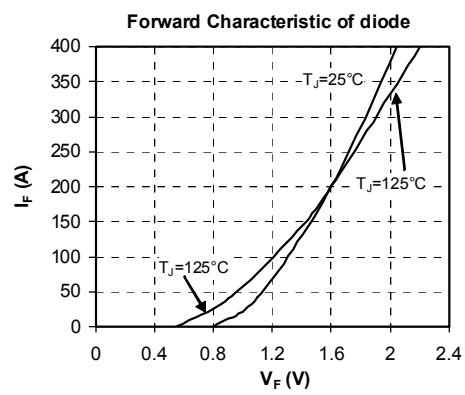
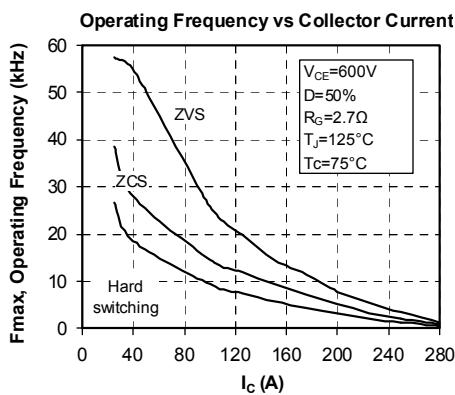
			<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R_{thJC}	Junction to Case Thermal Resistance	IGBT			0.14	°C/W
		Diode			0.25	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, I isol<1mA, 50/60Hz		2500			V
T_J	Operating junction temperature range		-40		150	°C
T_{STG}	Storage Temperature Range		-40		125	
T_C	Operating Case Temperature		-40		100	
Torque	Mounting torque	To heatsink	M6	3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package Weight				280	g

SP6 Package outline (dimensions in mm)

 See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com



Typical Performance Curve





Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S and Foreign patents pending. All Rights Reserved.